

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6630489

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUIYING DING	02/01/2021
JUNFENG LIU	02/01/2021
LONGNAN JIN	02/01/2021
HEINRICH KARRER	02/10/2021
THOMAS SCHMIDT	02/09/2021
RECEIVING PARTY DATA	
Name:	VISHAY GENERAL SEMICONDUCTOR, LLC
Street Address:	63 LANCASTER AVENUE
City:	MALVERN
State/Country:	PENNSYLVANIA
Postal Code:	19355
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17059084
CORRESPONDENCE DATA	
Fax Number:	(215)568-6499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2155686400
Email:	ajones@vklaw.com
Correspondent Name:	RYAN W. O'DONNELL
Address Line 1:	VOLPE KOENIG
Address Line 2:	30 SOUTH 17TH STREET, 18TH FLOOR
Address Line 4:	PHILADELPHIA, PENNSYLVANIA 19103
ATTORNEY DOCKET NUMBER:	VIIV041-19-DIOD-002-US00
NAME OF SUBMITTER:	RYAN W. O'DONNELL
SIGNATURE:	/RYAN W. O'DONNELL/
DATE SIGNED:	03/30/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 8

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page1.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page2.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page3.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page4.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page5.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page6.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page7.tif

source=VIIV041-19-DIOD-002-US00 - Combined Declaration and Assignment (Executed)#page8.tif

COMBINED DECLARATION AND ASSIGNMENT

DECLARATION

With respect to the invention titled, **PACKAGING PROCESS FOR PLATING WITH SELECTIVE MOLDING**, the undersigned has authorized the application as identified by the attorney docket number and as assigned United States Patent Application No. 17/059,084, filed on November 25, 2020, which is a 371 U.S. National Phase of International Patent Application No. PCT/US2020/017135, filed on February 7, 2020.

As the below named inventor, I hereby state and declare that:

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than 5 years, or both.

ASSIGNMENT

With respect to the invention titled, **PACKAGING PROCESS FOR PLATING WITH SELECTIVE MOLDING**, assigned United States Patent Application No. 17/059,084, filed on November 25, 2020, which is a 371 U.S. National Phase of International Patent Application No. PCT/US2020/017135, filed on February 7, 2020, which claims priority to Chinese Patent Application No. 201911348978.6, filed December 24, 2019:

Assignee	VISHAY GENERAL SEMICONDUCTOR, LLC
Assignee State or Country of Incorporation	Pennsylvania
Assignee Address	63 Lancaster Avenue Malvern, PA 19355

Assignee is desirous of acquiring the entire right, title and interest in the invention, all applications for and all letters patent issued on the invention.

For good and valuable consideration, the receipt and sufficiency of which is acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee and assignee's successors, assigns and legal representatives the entire right, title and interest in the invention and all patent applications thereon, including, but not limited to, United States Patent Application No. 17/059,084, International Patent Application No. PCT/US2020/017135, and Chinese Patent Application No. 201911348978.6, and all divisions and continuations thereof, and in all letters patent and applications for letters patent, including all reissues and reexaminations thereof, throughout the world, including the right to claim priority under the Paris Convention or other treaty.

Atty. Docket No. VIIV041-19-DIOD-002-US00

It is agreed that the undersigned shall be legally bound, upon request of the assignees, to supply all information and evidence relating to the making and practice of the invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention throughout the world for the benefit of the assignees, and to execute all instruments proper to carry out the intent of this instrument.

The undersigned warrants that the rights and property herein conveyed are free and clear of any encumbrance.

This Assignment may be executed in multiple counterparts, each of which shall be deemed to be an original of this Assignment. Additionally, the undersigned hereby authorizes our attorneys to collect the signature pages of each executed counterpart and to attach those signature pages to a single copy of this instrument, which single copy and attached signature pages together shall constitute an original of this Assignment.

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name ⇨ Huiying DING

Inventor's Signature ⇨ Huiying DING

Date ⇨ 2/1, 2021

Signed at ⇨ Tianjin, China
(City and Country)

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name ⇒ Junfeng LIU _____

Inventor's Signature ⇒ Junfeng LIU. _____

Date ⇒ 2/1/2021 _____

Signed at Tianjin, China. _____
(City and Country)

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

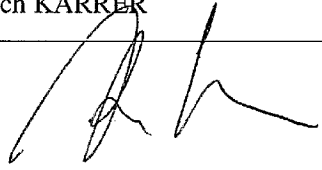
Inventor's Name ⇨ Longnan JIN _____

Inventor's Signature ⇨ *Longnan JIN* _____

Date ⇨ *2/1, 2021* _____

Signed at ⇨ *Tian Jin, China* _____
(City and Country)

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name ⇒ Heinrich KARRER
Inventor's Signature ⇒ 
Date ⇒ 10.2.2021
Signed at ⇒ VOCHLABRUCH, AUSTRIA
(City and Country)

**SIGNATURE SHEET FOR
DECLARATION AND ASSIGNMENT**

Inventor's Name ⇨ Thomas SCHMIDT

Inventor's Signature ⇨

Thomas Schmidt

⇨

Date

9.2.2021

Signed at

Wöcklabruck, AUSTRIA
(City and Country)